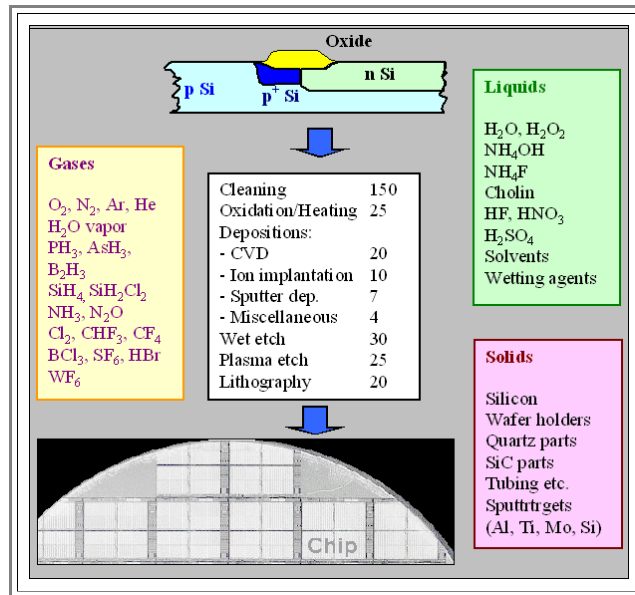


## Processes and Materials II

Here is the rest of the processes

- A few more materials are needed, especially solids in the form of "sputter targets".
- A great total of about **450** process- and control steps are needed.

Illustration



We don't have a chip yet - we only have unpackaged chips on a wafer.

- Next, the wafer has to be cut and the chips that work (this needs a measurement) are packaged.
- Packaging, although not needing processes at very small dimensions, is not simple either.
- To continue, use the link**